SOIC-to-JEDEC TO Adapter

FEATURES
- 8-position SOIC footprint on the top and a circular, 8-pin JEDEC TO male pin footprint on the bottom. IC now available only in 8-position SOIC packages, can be readily mounted on boards having JEDEC TO thru-hole footprints without having to redesign the board.
- Consult factory for mounting of consigned chips.

GENERAL SPECIFICATIONS
- ADAPTER BOARD: FR-4, 0.062 [1.58] thick, with 1-oz. Cu traces both sides
- MALE PIN: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- MALE PIN PLATING: 200µ [5.08µ] Sn/Pb 93/7 ASTM B579-73 over 100µ [2.54µ] Ni per SAE-AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS
- SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.

ORDERING INFORMATION

<table>
<thead>
<tr>
<th>P/N</th>
<th>Dim “C”</th>
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<tbody>
<tr>
<td>1109814</td>
<td>0.200[5.08]</td>
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<tr>
<td>08-301296-10</td>
<td>0.300[7.62]</td>
</tr>
<tr>
<td>08-305479-10</td>
<td>0.270[6.85]</td>
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</tbody>
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CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. NOTE: Aries reserves the right to change product general specifications without notice.

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

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